

with reference to Fig. 34 and Fig. 35.

First of all, when forming an anisotropic conductive layer directly on the circuit board 4, a first resin sheet is stuck onto the circuit board 4, and a second resin sheet is stuck onto the sheet. When there is a great amount of inorganic filler 6f in the first resin sheet at this time, there is the result as shown in Fig. 28A or Fig. 30. In the converse case, there is the result as shown in Fig. 28B or Fig. 31. That is, in the former case, the first resin sheet is a resin sheet corresponding to the portion 701 or the second resin layer 6y that has a great amount of inorganic filler 6f. In the latter case, the sheet is a resin sheet corresponding to the portion 700 or the first resin layer 6x that has a small amount of inorganic filler 6f.

When a third resin sheet is further formed on the second resin sheet together with the first resin sheet and the third resin sheet corresponding to the portion 700 or the first resin layer 6x that has a small amount of inorganic filler 6f, there is the result as shown in Fig. 28C or Fig. 32A.

It is also acceptable to preliminarily form a first resin sheet 673 and a second resin sheet 674 on a base film 672 that is called a separator in this order (only this case is shown in Fig. 34 and Fig. 35) or

reversely or together with a third resin sheet stuck as shown in Fig. 34 and Fig. 35. In this case, as shown in Fig. 34 and Fig. 35, the plurality of resin sheets 673 and 674 are stuck while heating at need by means of a vertical pair of heatable rollers 670 and 270 as shown in Fig. 34 and Fig. 35. Subsequently, by cutting the formed resin sheet body 671 every prescribed dimension, there is the anisotropic conductive film sheet 10 as shown in any one of Figs. 28A through 28C, Figs. 29A through 29C and Figs. 30 through 32.

When producing an anisotropic conductive film sheet body of the continuous anisotropic conductive film sheets 10 as another modification example, epoxy and inorganic fillers dissolved in a solvent are applied to a base film called a separator by the doctor blade method or the like. This solvent is dried to produce the anisotropic conductive film sheet body.

At this time, a liquid insulating resin in which the density of the inorganic filler 6f is low or no inorganic filler 6f is contained is once applied as a first layer to the base film, and according to circumstances, the applied first layer is dried. When the layer is not dried, a certain amount of the inorganic filler 6f of the second layer is mixed with the first layer, providing a structure in which the inorganic filler distribution is inclined as

shown in Fig. 33.

A liquid insulating resin mixed with a greater amount of inorganic filler 6f than that of the first layer is applied as a second layer onto the first layer formed that has been applied and formed. By drying the second layer, there is formed an anisotropic conductive film sheet body of a two-layer structure in which the first layer and the second layer are formed on the base film. By cutting the anisotropic conductive film sheet body every specified dimension, there is an anisotropic conductive film sheet 10 as shown in Fig. 28A, Fig. 29A and Fig. 30.

When the layer that has a small amount of inorganic filler 6f is arranged on the board side, the anisotropic conductive film sheet body of a two-layer structure can be formed by a process reverse to the above, i.e., by forming the second layer on the base film and thereafter forming the first layer on the second layer. By cutting the anisotropic conductive film sheet body every specified dimension, there is an anisotropic conductive film sheet 10 as shown in Fig. 28B, Fig. 29B and Fig. 31.

The insulating resin 6m in which the density of the inorganic filler 6f is low or no inorganic filler 6f is contained is once applied and dried as the first layer (sometimes omitted), and an insulating resin mixed with a greater amount of the inorganic filler 6f or with no